

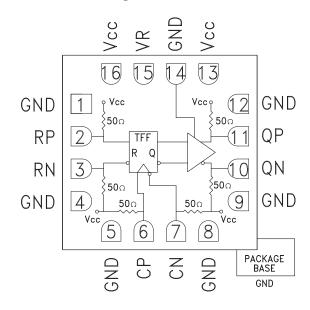


Typical Applications

The HMC749LC3C is ideal for:

- · Serial Data Transmission up to 26 Gbps
- High Speed Frequency Divider (up to 26 GHz)
- · Broadband Test & Measurement
- · RF ATE Applications

Functional Diagram



Features

Supports Clock Frequencies up to 26 GHz

Differential & Singe-Ended Operation

Fast Rise and Fall Times: 18 / 17 ps

Low Power Consumption: 270 mW typ.

Programmable Differential

Output Voltage Swing: 600 - 1100 mV

Propagation Delay: 95 ps Single Supply: +3.3V

16 Lead Ceramic 3x3mm SMT Package: 9mm²

General Description

The HMC749LC3C is a T Flip-Flop w/Reset designed to support clock frequencies as high as 26 GHz. During normal operation, with the reset pin not asserted, the output toggles from its prior state on the positive edge of the clock. This results in a divide-bytwo function of the clock input. Asserting the reset pin forces the Q output low regardless of the clock edge state (asynchronous reset assertion). Reversing the clock inputs allows for negative-edge triggered applications. The HMC749LC3C also features an output level control pin, VR, which allows for loss compensation or for signal level optimization.

All input signals to the HMC749LC3C are terminated with 50Ω to Vcc on-chip, and may be either AC or DC coupled. inputs or outputs can be connected directly to a 50Ω Vcc terminated system, while DC blocking capacitors may be used if the terminating system is 50Ω ground. The HMC749LC3C operates from a single +3.3V DC supply and is available in a ceramic RoHS compliant 3x3 mm SMT package.

Electrical Specifications, $T_A = +25$ °C Vcc = +3.3V

Parameter	Conditions	Min.	Тур.	Max	Units
Power Supply Voltage		3	3.3	3.6	V
Power Supply Current			82		mA
Maximum Clock Rate			26		GHz
Input High Voltage		2.8		3.8	V
Input Low Voltage		2.1		3.3	V
Input Return Loss	Frequency <13 GHz		10		dB
Outrook Associationals	Single-Ended, peak-to-peak		550		mVpp
Output Amplitude	Differential, peak-to-peak		1100		mVpp
Output High Voltage			3.25		mV
Output Low Voltage			2		mV



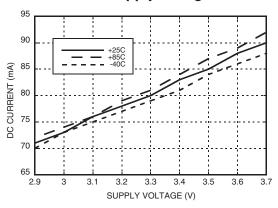


Electrical Specifications, (continued)

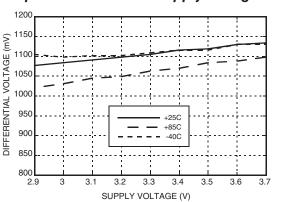
Parameter	Conditions	Min.	Тур.	Max	Units
Output Rise / Fall Time	Differential, 20% - 80%		18 / 17		ps
Output Return Loss	Frequency <13 GHz		10		dB
Random Jitter Jr	rms ^[1]			0.2	ps rms
Deterministic Jitter, Jd	peak-to-peak, 2 ¹⁵ -1 PRBS input [2]		2		ps, pp
Propagation Delay Clock to Q, td			95		ps
Propagation Delay Reset to Q, tdr			125		ps
Set Up & Hold Time, t _{SH}			6		ps

^[1] Upper limit of random jitter, J_R , determined by measuring and integrating output phase noise with a sinusodal input at 5, 10, and 13.5 GHz over temperature.

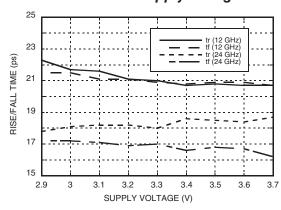
DC Current vs. Supply Voltage [1] [2]



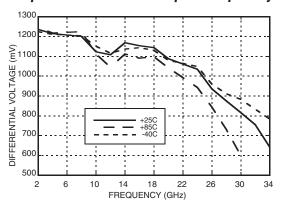
Output Differential vs. Supply Voltage [1][2]



Rise / Fall Time vs. Supply Voltage [3] [1]



Output Differential vs. Input Frequency [1]



[1] VR = +3.3V

[2] Frequency = 12 GHz

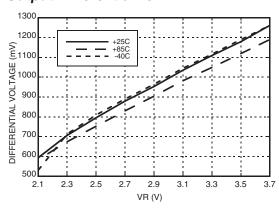
[3] Frequency = 24 GHz

^[2] TBD

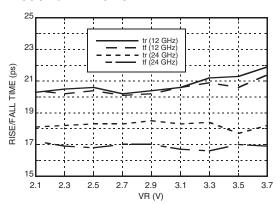




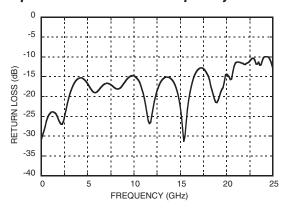
Output Differential vs. VR [2]



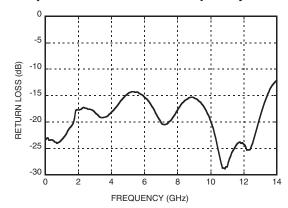
Rise / Fall Time vs. VR [2]



Input Return Loss vs. Frequency



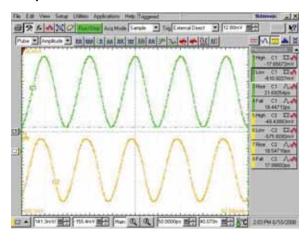
Output Return Loss vs. Frequency







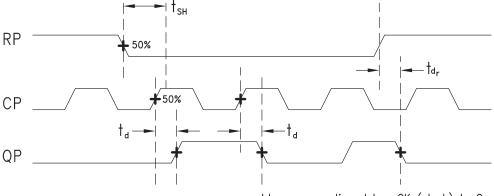
Output Waveform



[1] Test Conditions:

Waveform generated with a CW signal source input at 24 GHz. Diagram data presented on a Tektronix CSA 8000. Device is AC coupled to scope.

Timing Diagram



td = propagation delay, CK (clock) to Q tdr = propagation delay, R (reset) to Q.

Truth Table

R	CK	Q	Q Next
0	L> H	0	1
0	L> H	1	0
1	Х	0	0 (ASYNC)
1	Х	1	0 (ASYNC)
Notes: R= RP - RN CK = CP - CN Q = QP - QN		H - Negative voltage level L - Positive voltage level	



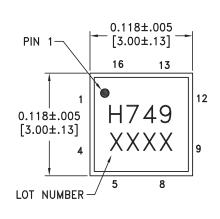


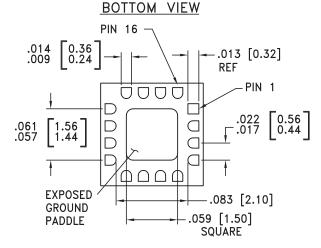
Absolute Maximum Ratings

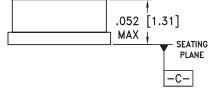
Power Supply Voltage (Vcc)	-0.5V to +3.7V	
Input Signals	Vcc - 2V to Vcc + 0.5V	
Output Signals	+1V to +3.7V	
Storage Temperature	-65°C to +150°C	
Operating Temperature	-40°C to +85°C	



Outline Drawing







NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA
- 2. LEAD AND GROUND PADDLE PLATING:
- 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- 6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.
- 7. PADDLE MUST BE SOLDERED TO GND.





Pin Descriptions [1]

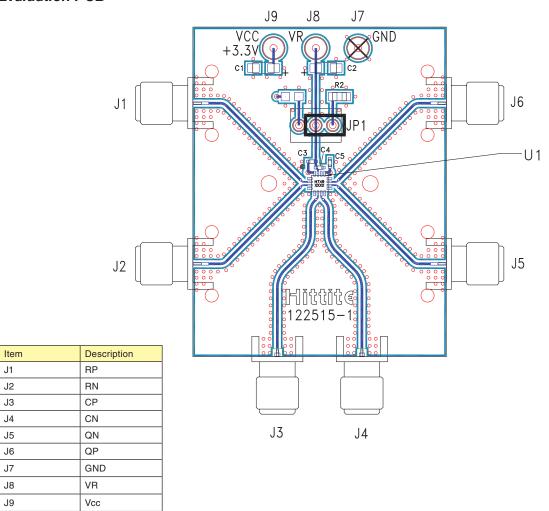
Pin Number	Function	Description	Interface Schematic
1, 4, 5, 8, 9, 12	GND	Signal Grounds	GND =
2, 3	RP, RN	Reset Inputs	GND 5000 RP, RN
6, 7	CP, CN	Clock Inputs	GND SOON CP, O
10, 11	QN, QP	Data Output	GND 500 QP, QN
13, 16	Vcc	Positive Supply	
14, Package Base	GND	Supply Ground	GND =
15	VR	Output level control. Output level may be adjusted by applying a voltage to VR per "Output Differential vs. VR" plot.	VR 0

^[1] Contact HMC for alternate pinouts





Evaluation PCB



List of Materials for Evaluation PCB 122517 [1]

Item	Description	
J1 - J6	PCB Mount SMA RF Connectors	
J7 - J9	DC Pin	
JP1	Shorting Jumper	
C1, C2	4.7 μF Capacitor, Tantalum	
C3 - C5	100 pF Capacitor, 0402 Pkg.	
R2	10 Ohm Resistor, 0603 Pkg.	
U1	HMC749LC3C	
PCB [2]	122515 Evaluation Board	

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed packaged base should be connected to GND. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Arlon 25FR





Application Circuit

